



# **Electron Induced Damage in Silicon**

#### -TRIM and TCAS Simulations-

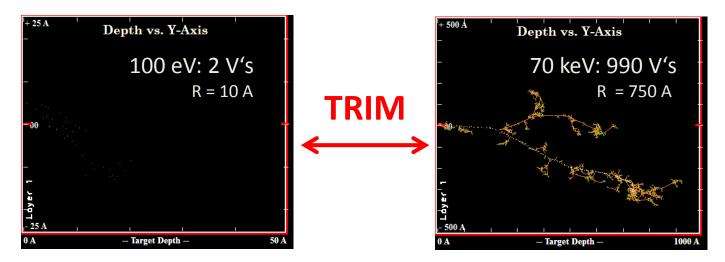
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Outline:

- Motivation
- Mott-formula and approximations
- Recoil-Energy Distributions
- Partition Ratio and Damage Function
- TRIM and TCAS results
- Simulations, Random Walk
- Conclusions and Outlook

# **Motivation:**

- Damage caused by heavy particles (n, p, π) result from a mixture of (a) point and (b) "cluster" defects
- Electron Irradiation in e.g. an energy range 1-30 MeV could offer an opportunity to correlate exp. results to (a) and (b)
- Maximum Si-recoil energy for 1 MeV is only <u>100 eV</u>, for 30 MeV it is <u>70 keV</u>, very similar to MeV neutrons!



#### Mott scattering

Scattering of relativistic electrons on Coulomb potential of point like charges (later on expanded by including screening): Dirac theory: Mott, Proc. Royal Soc. A124 (1929) and A135 (1932)

 $(d\sigma/d\Omega)_{Mott} = (d\sigma/d\Omega)_{Ruth} \cdot R_{Mott}$ ;  $(d\sigma/d\Omega)_{Ruth}$  relativistic Rutherford-scattering

 $R_{Mott} = A(E.\Theta) \cdot |F|^2 + B(Z,E,\Theta) \cdot |G|^2$ 

F, G complex functions, expansion with  $D_k(\alpha Z,\beta)$  and Legendre Polynoms  $P_k(\cos \Theta)$ Expansion only conditionally convergent, exact numerical solution difficult!

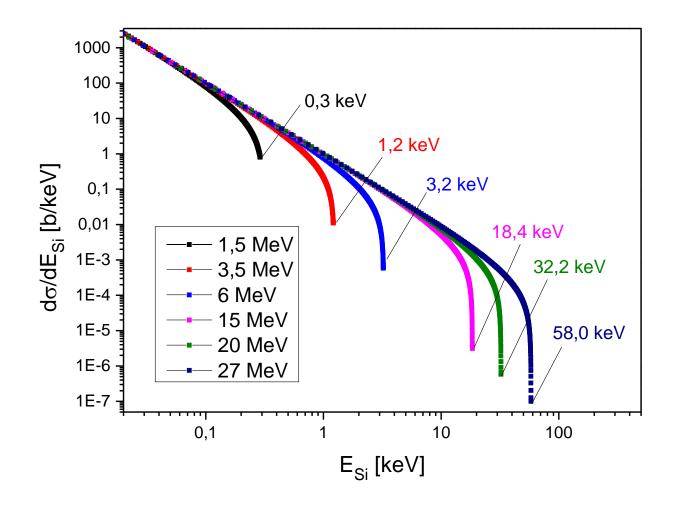
Numerical approximation by **T. Lijian et al: Rad. Phys. Chem. 45, 235 (1995):**   $R_{Lijian}(Z, E_k, \Theta) = \sum_{j=0}^{4} a_j (E_k) \cdot (1 - \cos \theta)^{j/2}$  und  $a_j (E_k) = \sum_{k=1}^{6} d(j, k) \cdot (\beta - \beta^*)^{k-1}$ Deviations from exact Mott: < 1% for 30 keV-900 MeV; Z = 1-89

Be aware of simple formula, often found in textbooks:  $d\sigma/d\Omega = (d\sigma/d\Omega)_{R} \cdot (1-\beta^2 \sin^2 \Theta/2)$ 

Recent good approach also by: M.J. Broschini et al, Rad. Phys. Chem. , preprint April 2013

#### **Recoil Energy Distributions**

Mott scattering, Lijians approach



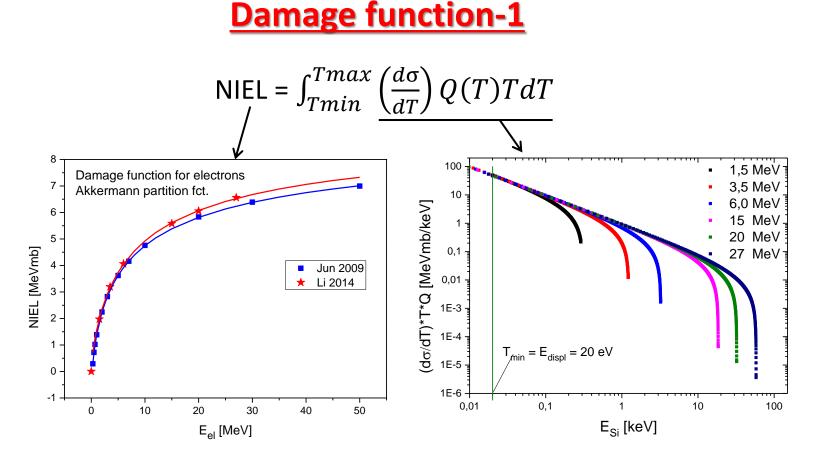
# **Partition Function Q**

describes that part of the energy loss which is responsible for NIEL J. Lindhard et al., Mat. Fys. Medd. Dan. Vid. Selsk., vol 33, pp. 1-42, 1963.

Practical applications: use analytical approximation M.T. Robinson, J. Nucl. Materials, vol.216, pp 1-28, 1994 J. Akkermann and J. Barak, IEEE Trans. Nucl. Sci. 53, 6 (2006) I. Jun et al.; IEEE Trans Nucl. Sci 56, 6 (2009)

For Si ions in Si:

$$\begin{split} &Z_1 = Z_2 = 14; \ M_1 = M_2 = 28 \\ &Q(\mathsf{T}) = [1 + k \cdot g(\epsilon)]^{-1}; \ k = 0,1463; \ \epsilon = \mathsf{T}/E_L, \ \mathsf{T} = \text{recoil energy}, \ E_L = 41,05 \ \text{keV} \\ &g(\epsilon) = 0,74422\epsilon + 1.6812\epsilon^{3/4} + 0,90565\epsilon^{1/6} \ \text{(Jun from Akkermann)} \end{split}$$



5% difference between present results and Jun, Jun: with atomic screening in relativ. Rutherford scattering

# **Monte Carlo Codes for Damage Cascades**

#### <u> TRIM:</u>

James F. Ziegler, IBM Last update: 2013

#### amorphous material

- Full damage cascades
- Broad choice of inputs
- graphic design
- Direct 2D graphic output
- No of vacancies
- Output tables: V(ok), I: ??

#### TCAS\*

Matthias Posselt, HZDR Last update: April 2014

#### Single crystal Si <100>

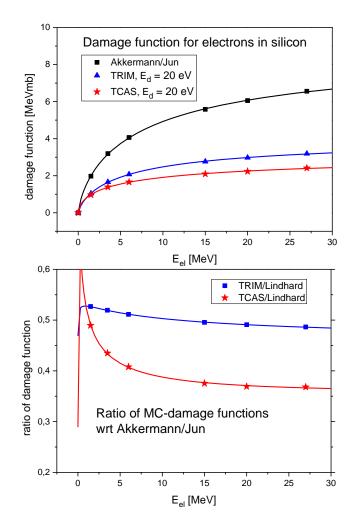
- Full damage cascades
- Broad choice of inputs
- LINUX by command
- graphic output included
- V and I tables
- ➤ + Intracasc. recombin.
- !! BCA-code (binary collision approximation), Zero K only !!

\* Many thanks to Matthias Posselt for continuous help

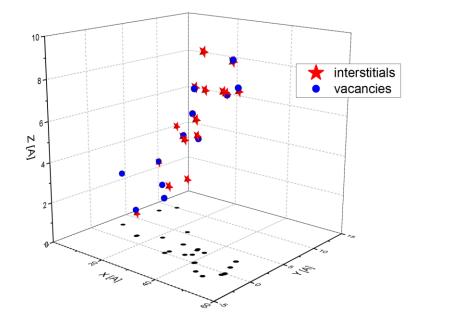
### **TRIM and TCAS results – Damage function-2**

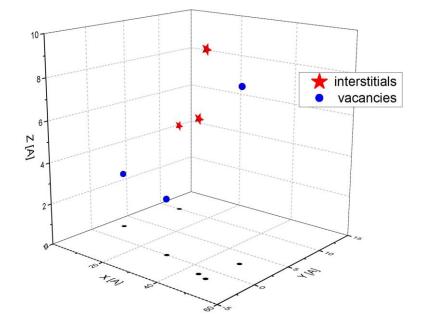
#### No of V's (TRIM) resp. V/I's (TCAS) per ion 1200 TRIM full cascade **TRIM Kinchin-Pease** 1000 no of vacancies per Si-ion TCAS full cascade 800 600 400 max recoil energy 200 for 27 MeV electrons 0 20 40 60 80 100 0 E<sub>Si</sub> [keV]

TRIM:  $E_d$ = 20 eV, average per 100 ions TCAS:  $E_d$ = 20 eV, average per 10 ions TRIM/TCAS = 1,8 Kinchin-Pease: approximation **TCAS believed to be more reliable** 



Example 1: E<sub>si</sub> = 1 keV (max. recoil for E<sub>el</sub> = 3,5 MeV)

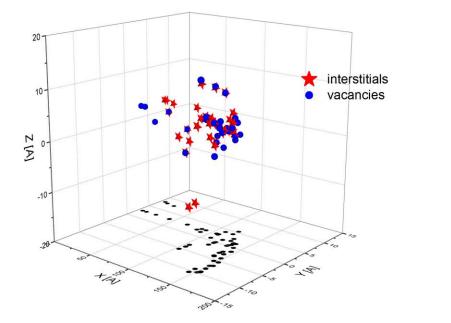


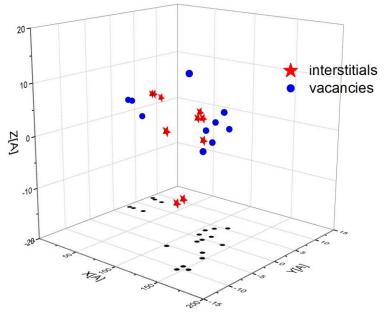


**16 V/I produced in cas**cade **Scale: x, y, z: 60, 20, 10 Å**  3 V/I after recombination (20%)

R<sub>rec</sub>= 4 Angstrom (lattice constant: 5,43 A)

Example 2:  $E_{si} = 3 \text{ keV}$  (max. recoil for  $E_{el} = 6 \text{ MeV}$ )

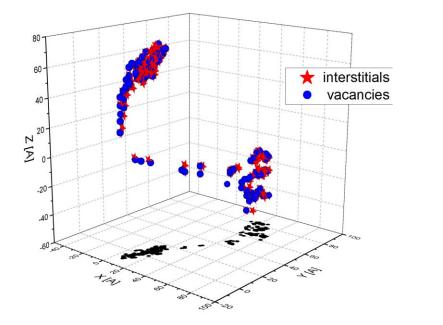


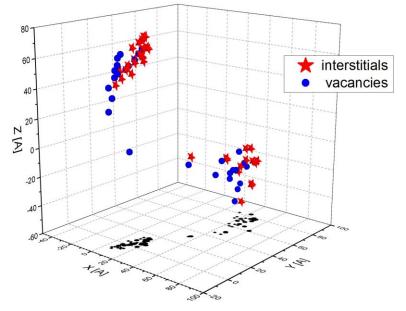


**36 V/I produced in cas**cade **Scale: x, y, z: 200, 30, 40 Å** 

10 V/I after recombination (20%)

Example 3:  $E_{si} = 20 \text{ keV}$  (max. recoil for  $E_{el} = 15 \text{ MeV}$ )

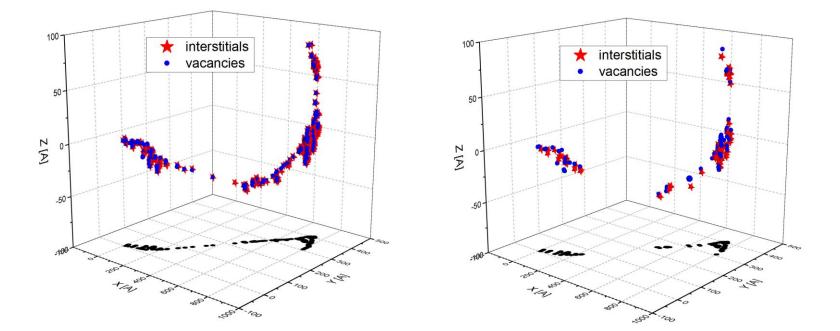




#### 210 V/I produced in cascade Scale: x, y, z: 150, 120, 140 Å

36 V/I after recombination (20%)

Example 3:  $E_{si} = 60 \text{ keV}$  (max. recoil for  $E_{el} = 27 \text{ MeV}$ )



474 V/I produced in cascade X,y,z: 1200, 600, 200 Å 86 V/I's after recombination (20%!)

Attn: these are only examples for one ion each! simulations done for 10 ions at each recoil energy

# **Random Walk of Defects**

#### **Contributed by Gregor**

# **Procedure:**

Input from TCAS (original cascade without intra-cascade recombination)

- 1. Correct for "doubles", if so move V or I by one lattice distance
- 2. Do initial recombination of V-I, after that:  $V+V->V_2$  and  $I+I->I_2$
- 3. Start with the random walk:
  - a. Find minimum distance *d* between any two I or V.
  - b. Set "adaptive time step" according  $t_{step} = \frac{d^2}{2 \cdot D_{VI}}$
  - c. Move all defects with steps in *x*, *y*, *z* distributed randomly according to Gaussian with width given by  $\sigma = \sqrt{2 \cdot D \cdot t_{step}}$
  - Loop over all defects and look for interactions. If two defects interact, create (or annihilate) a new defect with given properties and include it in the next step (parents -> child hierarchy)
  - e. Repeat from step a-e as many times as required

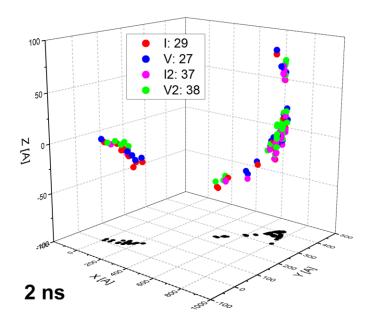
# **Assumptions**

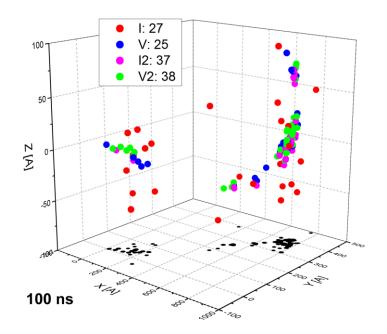
- Diffusion constants: S.M. Myers et al. JAP 104 (2008). dependece on charge states neglected
- D assumed independent on lattice orientation
- Reaction occurs if two defects are within given radius at given time step -(ON/OFF) decision, will be improved to calculate probability based on distance. This is one of the most important improvements needed.



- TCAS for generation of V,I
- Random Walk is a c++ ROOT based library.
  - Inputs:
    - Table with interaction radii,  $R_{VI} = 4 A$ ,  $R_{VV} = 7.7 A$ ,  $R_{II} = 7.9 A$
    - Table with possible reactions, so far only: V+I, V+V, I+I
    - Diffusion constants, only for I and V, V<sub>2</sub> and I<sub>2</sub> assumed immobile
  - Visualization based on ROOT

# Example: Si-recoil energy of 60 keV

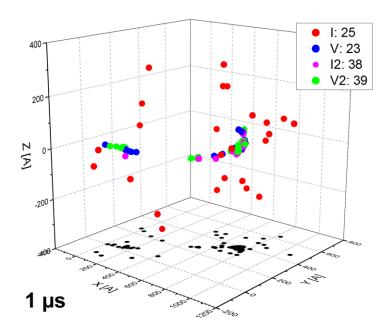




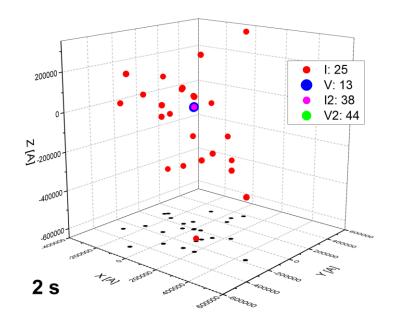
t=2 ns: not much migrations yet, a lot of I2 and V2 formed in or close to initial cascade Scale: x, y, z: 1200, 600, 200 Å

t= 100 ns: I2 and V2 not much changed I's migrate out of the initial cascade Scale: x, y, z: 1200, 600, 200 Å

# Example: Si-recoil energy of 60 keV

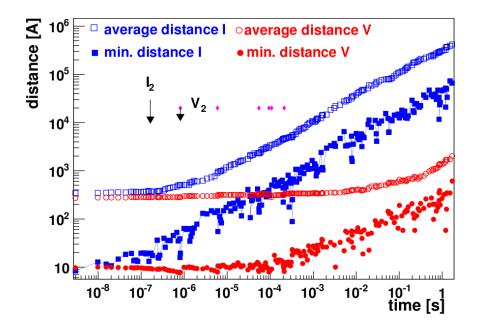


t = 1 μs, original cascade still in place (I2, V2 assumed to be immobile), ongoing fast migration of I's Scale: x, y, z: 1400, 1000, 1000 Å



t = 2s, 25 of the initial 103 I's have moved throughout the detector volume! Finally: more V2 than I2 formed! Scale: x, y, z: 100, 120, 100 μm!

# Example: Si-recoil energy of 60 keV



At 1 s: average distance I: 32 μm!

At 1 s: average distance V: 0,14 μm!

Interstitials migrate much faster than vacancies, hence they evade disordered regions more likely, More V<sub>2</sub> than I<sub>2</sub> formed as seen for t > 1 $\mu$ s

#### **Conclusions and Outlook**

- Mott scattering implemented from Lijians parameterization, be aware of simple textbook equations, especially for heavier atoms
- Partition function used from Akkermann and Jun, small deviations in displacement function due to atomic screening in Rutherford equation (Jun)
- Displacement function derived from TRIM and TCAS deviate from traditional approach, TCAS believed to be more reliable than TRIM
- TCAS offers simulation for single crystals (Si: <100>) and a direct output for both vacancies and interstitials plus recombination within initial cascade, leaving 20% surviving for migration
- Random walk studies reproduce TCAS recombinations and show development of I, V, V-V and I-I as fct. of time. Interstitials move faster and hence evade damage sites especially seen after longer times (μs)
- TRIM and TCAS are binary code collision approximations, describing damage production as sequence of 2 body interactions (cascades)
- More realistic (?): MD model, based on many body interactions, local heating, melting, amorphization, recrystallisation taken into account, see
  C. Inguimbert et al., IEEE NS 57, 4 (2010) and literature cited there
- Future approach: start with MD, followed by random walk as in this report

#### **Kinchin-Pease approximation**

Kinchin and R.S. Pease, The displacement of atoms in solids by radiation, Rep. Prog. Phys., vol. 18, p. 1, 1955

Describes number  $N_{FP}$  of produced Frenkel pairs for an energy  $E_{PKA}$  of a primary knock on atom by a simple analytic equation:

$$N_{FP} = 0.8 \cdot (E_{PKA} / 2T_{d,av})$$
 for  $E_{PKA} > 2T_{d,av} / 0.8$ 

 $T_{d,av}$  : average displacement energy

This simple equation should be taken with great care, see one of the figures (slide 8) in this report. It is incuded in SRIM/TRIM as one of the options, does not describe TRIM nor TCAS results.

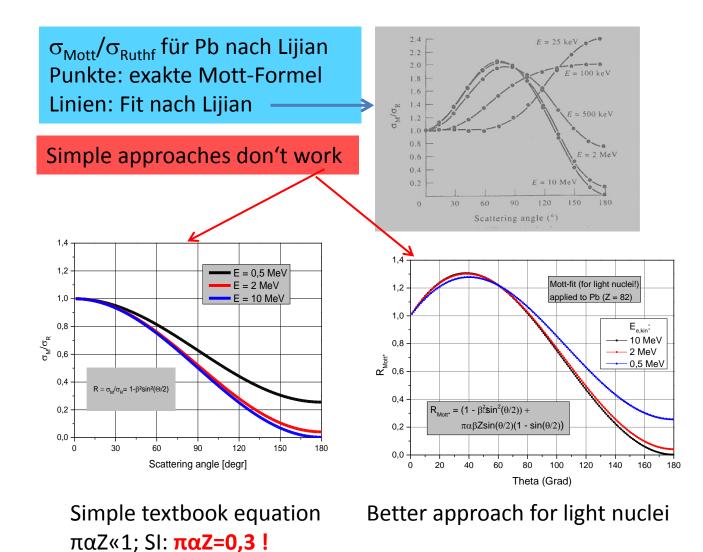
### **Molecular Dynamics Simulation**

Based on many body interactions in contrast to BCA, binary code 2 body collisions, as in TRIM, TCAS.

- In contrast to Kinchin-Pease non-linear effects primarily at low E<sub>PKA</sub>
- > Displacements can be generated even for  $E_{PKA} < E_d$  !
- > Initially huge no of FP produced, cooling down to RT within few ps
- After stable condition reached (< 10 ps) no of FP roughly as in BCA</p>
- Isolated point defects are predominantly interstitials (see Gregor)
- > Amorphous clusters may be produced in cascade core

*For further reading start with citations given in:* 

*C. Inguimbert et al: "Effective NIEL" in Silicon: Calculation Using MolecularDynamics Simulation Results, IEEE NS Vol 57, No 4, 2010* 



24th RD50 workshop, Bucharest, 11-13 June 2014